

# Global and United States Advanced Packaging Market Research by Company, Type & Application 2013-2025

<https://marketpublishers.com/r/GE87493764DEN.html>

Date: April 2018

Pages: 116

Price: US\$ 2,000.00 (Single User License)

ID: GE87493764DEN

## Abstracts

### SUMMARY

During the final stages of semiconductor development, a tiny block of materials (the silicon wafer, logic, and memory) is wrapped in a supporting case that prevents physical damage and corrosion and allows the chip to be connected to a circuit board. Typical packaging configurations have included the leadless chip carriers and pin-grid arrays of the 1980s, the system-in-package and package-on package setups of the 2000s, and, most recently, 2-D integrated-circuit technologies such as wafer-level, flip-chip, and through silicon via setups.

Market Segment as follows:

By Type

3.0 DIC

FO SIP

FO WLP

3D WLP

WLCSP

2.5D

## Filp Chip

### By Application

Analog & Mixed Signal

Wireless Connectivity

Optoelectronic

MEMS & Sensor

Misc Logic and Memory

Others

### By Company

ASE

Amkor

SPIL

Stats Chippac

PTI

JCET

J-Devices

UTAC

Chipmos

Chipbond

STS

Huatian

NFM

Carsem

Walton

Unisem

OSE

AOI

Formosa

NEPES

The main contents of the report including:

Section 1:

Product definition, type and application, global and United States market overview;

Section 2:

Global and United States Market competition by company;

Section 3:

Global and United States sales revenue, volume and price by type;

Section 4:

Global and United States sales revenue, volume and price by application;

Section 5:

United States export and import;

Section 6:

Company information, business overview, sales data and product specifications;

Section 7:

Industry chain and raw materials;

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SWOT and Porter's Five Forces;  
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